



MMDT4413

COMPLEMENTARY PAIR SMALL SIGNAL TRANSISTOR IN SOT363

Features

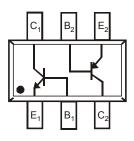
- **Epitaxial Die Construction**
- Two Internally Isolated NPN/PNP Transistors in One Package NPN = 4401
 - PNP = 4403
- Ideal for Medium Power Amplification and Switching
- Ultra-Small Surface Mount Package
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: SOT363
- Case Material: Molded Plastic, "Green" Molding Compound. • UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Finish. Solderable per MIL-STD-202, Method 208 3
- Weight: 0.006 grams (approximate)



Top View



Device Schematic Top View

Ordering Information (Note 4)

Part Number	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
MMDT4413-7-F	K13	7	8	3,000

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green"

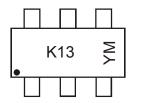
and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information

Notes:



K13= Product Type Marking Code YM = Date Code Marking Y = Year (ex: A = 2013) M = Month (ex: 9 = September)

Date Code Ke	у											
Year	2010	201	11	2012	20	013	2014	2	2015	2016		2017
Code	Х	Y	*	Z		A	В		С	D		E
Month	Jan	Feb	Mar	Apr	Мау	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



Absolute Maximum Ratings: NPN, 4401 Type (Q₁) (@T_A = +25°C unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	60	V
Collector-Emitter Voltage	V _{CEO}	40	V
Emitter-Base Voltage	V _{EBO}	6	V
Collector Current	Ιc	600	mA

Absolute Maximum Ratings: PNP, 4403 Type (Q₂) (@T_A = +25°C unless otherwise specified.)

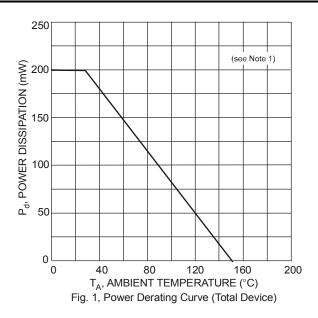
Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	-40	V
Collector-Emitter Voltage	V _{CEO}	-40	V
Emitter-Base Voltage	V _{EBO}	-5	V
Collector Current	Ιc	-600	mA

Thermal Characteristics – Total Device (@T_A = +25°C unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5) Total Device	PD	200	mW
Thermal Resistance, Junction to Ambient (Note 5)	$R_{ ext{ heta}JA}$	625	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150	°C

Note: 5. For a device mounted on minimum recommended pad layout with 1oz copper that is on a single-sided 1.6mm FR4 PCB; the device is measured under still air conditions whilst operating in a steady-state.

Thermal Characteristics – Total Device





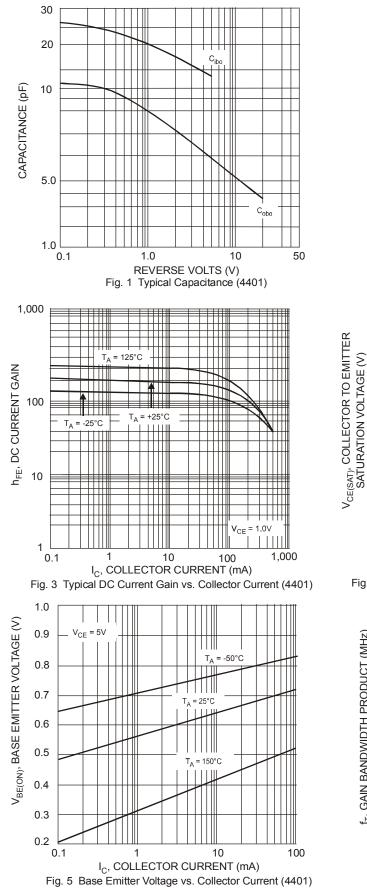
Electrical Characteristics, NPN 4401 Section (@T_A = +25°C unless otherwise specified.)

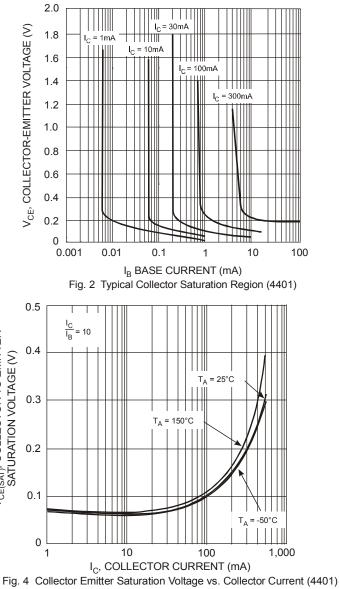
Characteristic	Symbol	Min	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 6)			•		<u>.</u>
Collector-Base Breakdown Voltage	BV _{CBO}	60	_	V	$I_{\rm C}$ = 100µA, $I_{\rm E}$ = 0
Collector-Emitter Breakdown Voltage	BV _{CEO}	40		V	I _C = 1.0mA, I _B = 0
Emitter-Base Breakdown Voltage	BV _{EBO}	6.0		V	I _E = 100 μA, I _C = 0
Collector Cutoff Current	ICEX	_	100	nA	V _{CE} = 35V, V _{EB(OFF)} = 0.4V
Base Cutoff Current	I _{BL}	_	100	nA	V _{CE} = 35V, V _{EB(OFF)} = 0.4V
ON CHARACTERISTICS (Note 6)					
DC Current Gain	hfe	20 40 80 100 40	 300 	_	$\begin{split} I_{C} &= \ 100 \mu A, \ V_{CE} &= \ 1.0 V \\ I_{C} &= \ 1.0 m A, \ V_{CE} &= \ 1.0 V \\ I_{C} &= \ 10 m A, \ V_{CE} &= \ 1.0 V \\ I_{C} &= \ 150 m A, \ V_{CE} &= \ 1.0 V \\ I_{C} &= \ 500 m A, \ V_{CE} &= \ 2.0 V \end{split}$
Collector-Emitter Saturation Voltage	V _{CE(SAT)}	—	0.40 0.75	V	I _C = 150mA, I _B = 15mA I _C = 500mA, I _B = 50mA
Base-Emitter Saturation Voltage	V _{BE(SAT)}	0.75	0.95 1.2	V	I _C = 150mA, I _B = 15mA I _C = 500mA, I _B = 50mA
SMALL SIGNAL CHARACTERISTICS					
Output Capacitance	C _{cb}	—	6.5	pF	V_{CB} = 5.0V, f = 1.0MHz, I _E = 0
Input Capacitance	C _{eb}	_	30	pF	V _{EB} = 0.5V, f = 1.0MHz, I _C = 0
Input Impedance	h _{ie}	1.0	15	kΩ	
Voltage Feedback Ratio	h _{re}	0.1	8.0	x 10 ⁻⁴	(-10)(1-10)mA = 10mA
Small Signal Current Gain	h _{fe}	40	500	—	V_{CE} = 10V, I _C = 1.0mA, f = 1.0kHz
Output Admittance	h _{oe}	1.0	30	μS	
Current Gain-Bandwidth Product	f⊤	250		MHz	V _{CE} = 10V, I _C = 20mA, f = 100MHz
SWITCHING CHARACTERISTICS	· · · · ·		-		
Delay Time	t _d	_	15	ns	V _{CC} = 30V, I _C = 150mA,
Rise Time	tr	_	20	ns	$V_{BE(off)}$ = 2.0V, I_{B1} = 15mA
Storage Time	ts	—	225	ns	V _{CC} = 30V, I _C = 150mA,
Fall Time	t _f	_	30	ns	I _{B1} = I _{B2} = 15mA

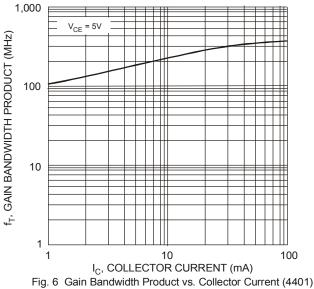
Note: 6. Measured under pulsed conditions. Pulse width \leq 300µs. Duty cycle \leq 2%











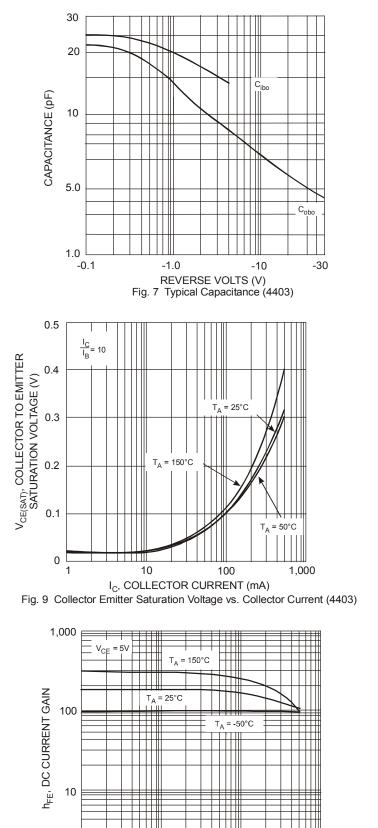


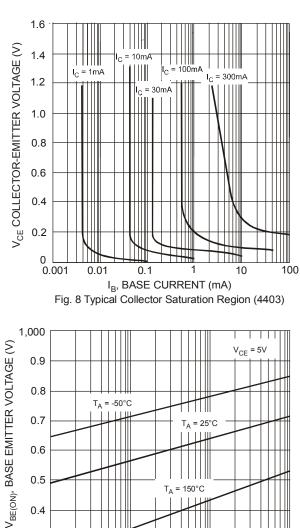
Electrical Characteristics, PNP 4403 Section (@T_A = +25°C unless otherwise specified.)

Characteristic	Symbol	Min	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 6)			-		
Collector-Base Breakdown Voltage	BV _{CBO}	-40	_	V	$I_{\rm C} = -100 \mu {\rm A}, \ I_{\rm E} = 0$
Collector-Emitter Breakdown Voltage	BV _{CEO}	-40	_	V	I _C = -1.0mA, I _B = 0
Emitter-Base Breakdown Voltage	BV _{EBO}	-5.0	_	V	$I_{\rm E} = -100 \mu A, I_{\rm C} = 0$
Collector Cutoff Current	I _{CEX}	_	-100	nA	V _{CE} = -35V, V _{EB(OFF)} = -0.4V
Base Cutoff Current	I _{BL}	_	-100	nA	V _{CE} = -35V, V _{EB(OFF)} = -0.4V
ON CHARACTERISTICS (Note 6)					
DC Current Gain	h _{FE}	30 60 100 100 20	 300 		$\begin{split} I_{C} &= -100 \mu A, V_{CE} = -1.0V \\ I_{C} &= -1.0 m A, V_{CE} = -1.0V \\ I_{C} &= -10 m A, V_{CE} = -1.0V \\ I_{C} &= -150 m A, V_{CE} = -2.0V \\ I_{C} &= -500 m A, V_{CE} = -2.0V \end{split}$
Collector-Emitter Saturation Voltage	V _{CE(SAT)}	—	-0.40 -0.75	V	I_{C} = -150mA, I_{B} = -15mA I_{C} = -500mA, I_{B} = -50mA
Base-Emitter Saturation Voltage	V _{BE(SAT)}	-0.75	-0.95 -1.30	V	I _C = -150mA, I _B = -15mA I _C = -500mA, I _B = -50mA
SMALL SIGNAL CHARACTERISTICS					
Output Capacitance	C _{cb}	_	8.5	pF	V _{CB} = -10V, f = 1.0MHz, I _E = 0
Input Capacitance	C _{eb}	_	30	pF	V_{EB} = -0.5V, f = 1.0MHz, I _C = 0
Input Impedance	h _{ie}	1.5	15	kΩ	
Voltage Feedback Ratio	h _{re}	0.1	8.0	x 10⁻⁴	V _{CE} = -10V, I _C = -1.0mA, f = 1.0kHz
Small Signal Current Gain	h _{fe}	60	500	—	$v_{CE} = -10v, IC = -1.0IIA, I = 1.0KIIZ$
Output Admittance	h _{oe}	1.0	100	μS	
Current Gain-Bandwidth Product	f⊤	200	—	MHz	V_{CE} = -10V, I_{C} = -20mA, f = 100MHz
SWITCHING CHARACTERISTICS					
Delay Time	t _d	_	15	ns	V _{CC} = -30V, I _C = -150mA,
Rise Time	tr	_	20	ns	$V_{BE(off)}$ = -2.0V, I_{B1} = -15mA
Storage Time	t _s	_	225	ns	V _{CC} = -30V, I _C = -150mA,
Fall Time	t _f		30	ns	$I_{B1} = I_{B2} = -15 \text{mA}$

Note: 6. Measured under pulsed conditions. Pulse width \leq 300µs. Duty cycle \leq 2%







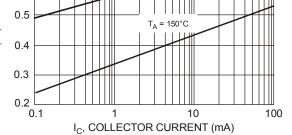
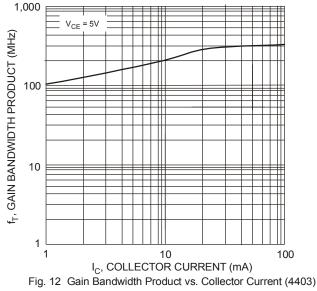


Fig. 10 Base-Emitter Voltage vs. Collector Current (4403)



10

1

1

1,000

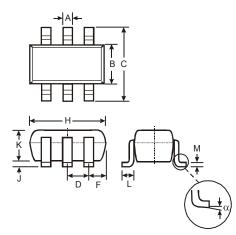
100

I_C, COLLECTOR CURRENT (mA) Fig. 11 DC Current Gain vs. Collector Current (4403)



Package Outline Dimensions

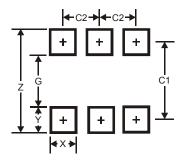
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



	SOT363						
Dim	Min	Max	Тур				
Α	0.10	0.30	0.25				
В	1.15	1.35	1.30				
С	2.00	2.20	2.10				
D		0.65 Ty	р				
F	0.40	0.45	0.425				
н	1.80	2.20	2.15				
J	0	0.10	0.05				
κ	0.90	1.00	1.00				
L	0.25	0.40	0.30				
М	0.10	0.22	0.11				
α	0°	8°	-				
All	All Dimensions in mm						

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
Z	2.5
G	1.3
X	0.42
Y	0.6
C1	1.9
C2	0.65



IMPORTANT NOTICE

DIODES INCORPORATED MAKES NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARDS TO THIS DOCUMENT, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION).

Diodes Incorporated and its subsidiaries reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to this document and any product described herein. Diodes Incorporated does not assume any liability arising out of the application or use of this document or any product described herein; neither does Diodes Incorporated convey any license under its patent or trademark rights, nor the rights of others. Any Customer or user of this document or products described herein in such applications shall assume all risks of such use and will agree to hold Diodes Incorporated and all the companies whose products are represented on Diodes Incorporated website, harmless against all damages.

Diodes Incorporated does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel. Should Customers purchase or use Diodes Incorporated products for any unintended or unauthorized application, Customers shall indemnify and hold Diodes Incorporated and its representatives harmless against all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized application.

Products described herein may be covered by one or more United States, international or foreign patents pending. Product names and markings noted herein may also be covered by one or more United States, international or foreign trademarks.

This document is written in English but may be translated into multiple languages for reference. Only the English version of this document is the final and determinative format released by Diodes Incorporated.

LIFE SUPPORT

Diodes Incorporated products are specifically not authorized for use as critical components in life support devices or systems without the express written approval of the Chief Executive Officer of Diodes Incorporated. As used herein:

A. Life support devices or systems are devices or systems which:

1. are intended to implant into the body, or

- 2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.
- B. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or to affect its safety or effectiveness.

Customers represent that they have all necessary expertise in the safety and regulatory ramifications of their life support devices or systems, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of Diodes Incorporated products in such safety-critical, life support devices or systems, notwithstanding any devices- or systems-related information or support that may be provided by Diodes Incorporated. Further, Customers must fully indemnify Diodes Incorporated and its representatives against any damages arising out of the use of Diodes Incorporated products in such safety-critical, life support devices or systems.

Copyright © 2013, Diodes Incorporated

www.diodes.com